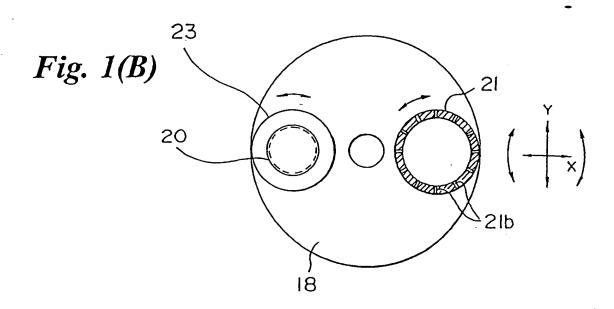
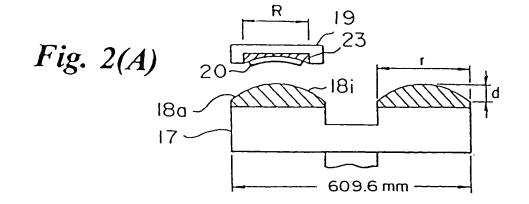


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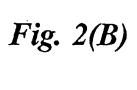




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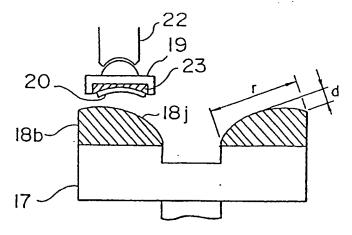


Fig. 2(C)  $4\mu$  (Flatness)

Wafer 6 inch  $\phi$ , (r = 280 mm, Flatness 4  $\mu$  Incase of  $d = 4 + 8 \mu$ )

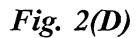
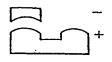
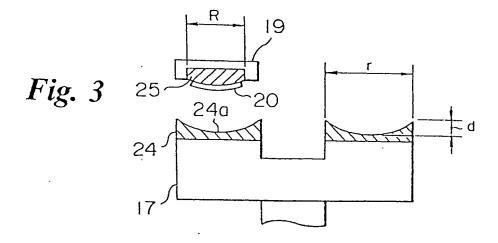


Fig. 2(E)







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Fig. 4(A)

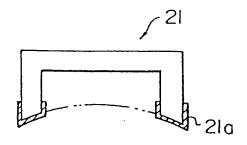


Fig. 4(B)

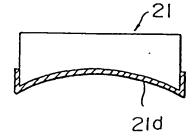
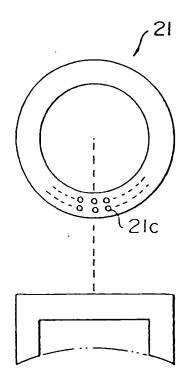


Fig. 4(C)



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Fig. 5

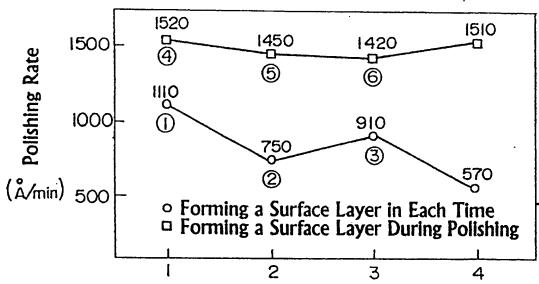
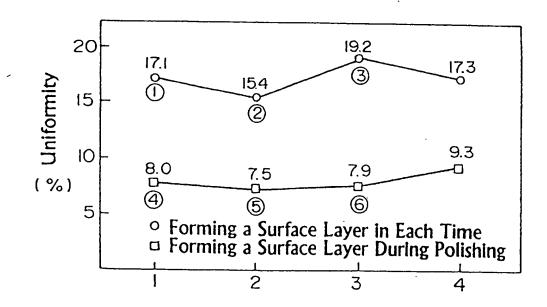


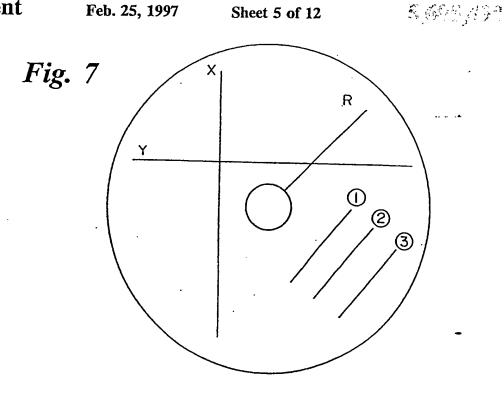
Fig. 6

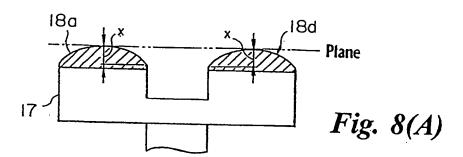


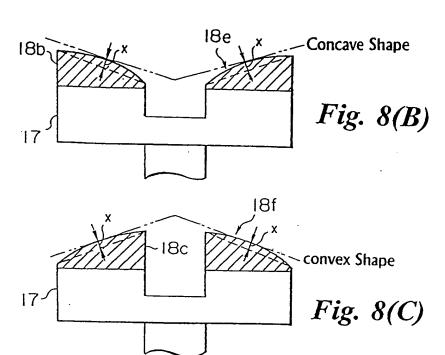
U.S. Patent

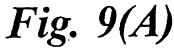
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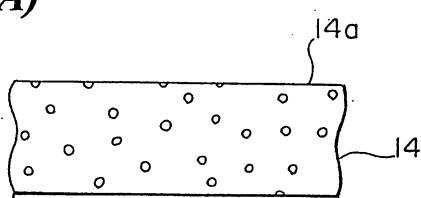
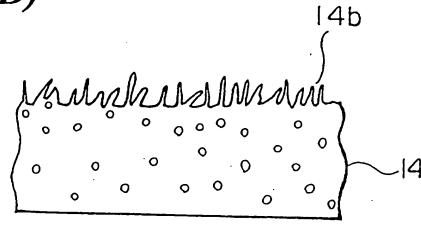
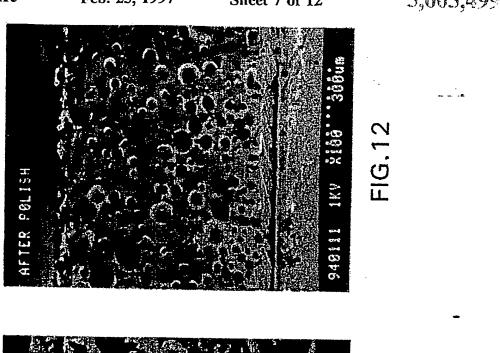


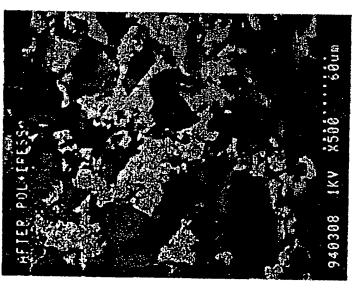
Fig. 9(B)

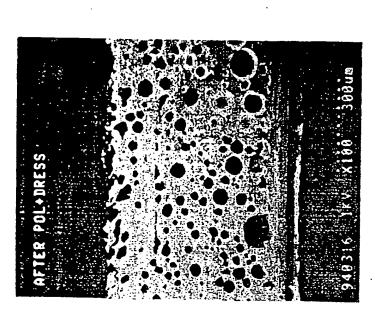


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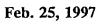




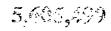
FIG

FIG. 10





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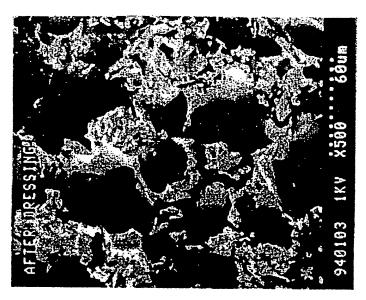


FIG.15

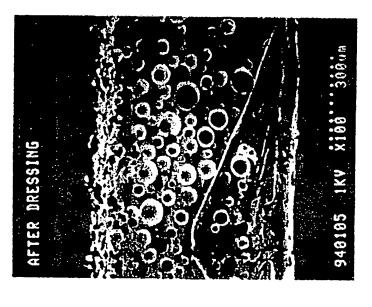
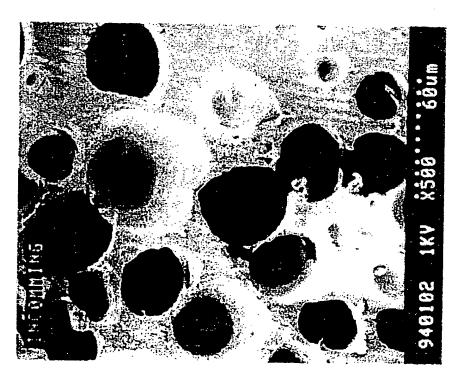


FIG.14



FIG. 13



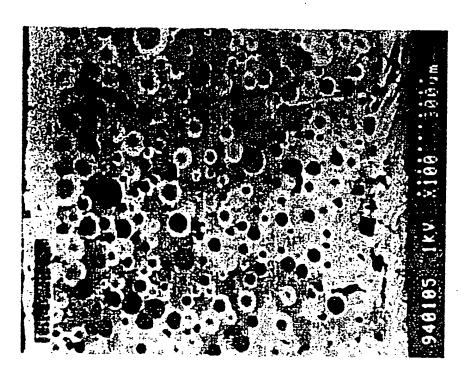


FIG. 16



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Fig. 18

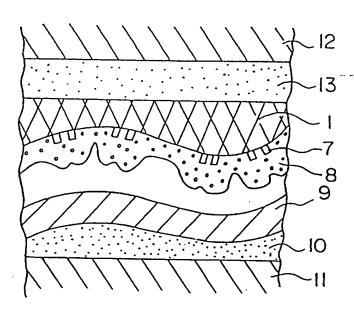


Fig. 19

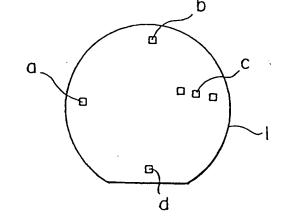


Fig. 20(A)

Straight Polishing

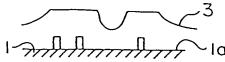
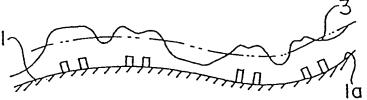


Fig. 20(B)



Polishing According to Unevenness of Wafer

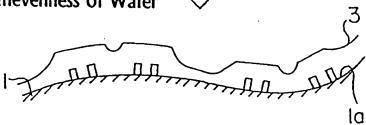


Fig. 21(A)

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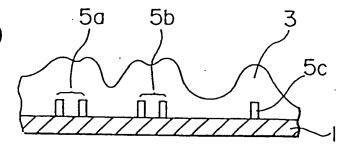


Fig. 21(B)

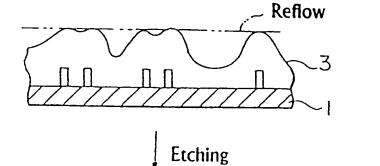
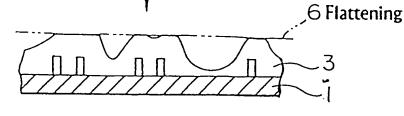


Fig. 21(C)



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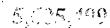


Fig. 22(A)



Fig. 22(B)

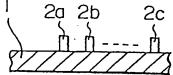


Fig. 22(C)

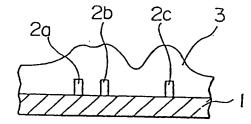


Fig. 22(D) 20\_

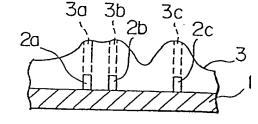


Fig. 22(E)

